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January 2015

# FDMS86150ET100

## N-Channel Shielded Gate PowerTrench<sup>®</sup> MOSFET

100 V, 128 A, 4.85 mΩ

### Features

- Extended  $T_J$  rating to 175°C
- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)} = 4.85 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 16 \text{ A}$
- Max  $r_{DS(on)} = 7.8 \text{ m}\Omega$  at  $V_{GS} = 6 \text{ V}$ ,  $I_D = 13 \text{ A}$
- Advanced Package and Silicon combination for low  $r_{DS(on)}$  and high efficiency
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

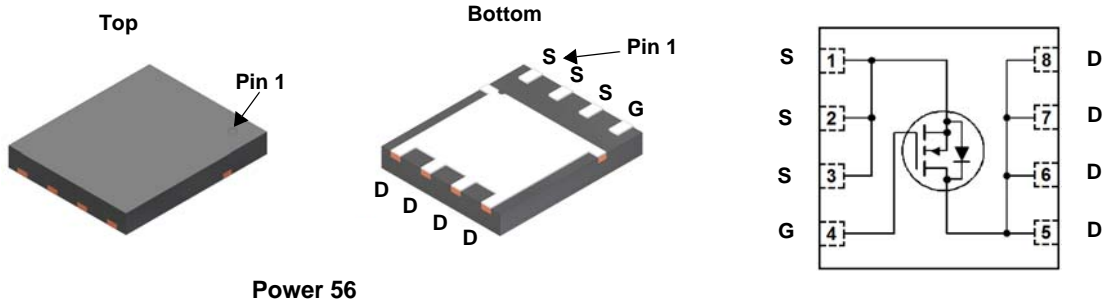


### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench<sup>®</sup> process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

### Applications

- Primary DC-DC MOSFET
- Secondary Synchronous Rectifier
- Load Switch



### MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	100	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current -Continuous $T_C = 25^\circ\text{C}$ (Note 5)	128	A
	-Continuous $T_C = 100^\circ\text{C}$ (Note 5)	90	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	16	
	-Pulsed (Note 4)	617	
$E_{AS}$	Single Pulse Avalanche Energy (Note 3)	726	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	187	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	3.3	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.8	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	45	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86150ET	FDMS86150ET100	Power 56	13 "	12 mm	3000 units

**Electrical Characteristics**  $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off Characteristics**

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0\text{ V}$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^{\circ}\text{C}$		72		mV/ $^{\circ}\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{ V}$ , $V_{DS} = 0\text{ V}$			$\pm 100$	nA

**On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^{\circ}\text{C}$		-10		mV/ $^{\circ}\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 16\text{ A}$		3.9	4.85	m $\Omega$
		$V_{GS} = 6\text{ V}$ , $I_D = 13\text{ A}$		6	7.8	
		$V_{GS} = 10\text{ V}$ , $I_D = 16\text{ A}$ , $T_J = 125\text{ }^{\circ}\text{C}$		7.3	9.1	
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}$ , $I_D = 16\text{ A}$		53		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	$V_{DS} = 50\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$		3055	4065	pF
$C_{oss}$	Output Capacitance			696	930	pF
$C_{rss}$	Reverse Transfer Capacitance			29	50	pF
$R_g$	Gate Resistance		0.1	0.7	3.6	$\Omega$

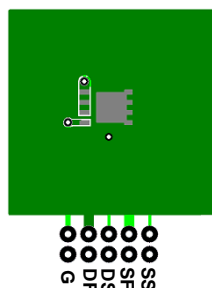
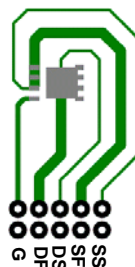
**Switching Characteristics**

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 50\text{ V}$ , $I_D = 16\text{ A}$ , $V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\text{ }\Omega$		18	33	ns
$t_r$	Rise Time			8.3	17	ns
$t_{d(off)}$	Turn-Off Delay Time			28	45	ns
$t_f$	Fall Time			6	12	ns
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{ V}$ to $10\text{ V}$	$V_{DD} = 50\text{ V}$ , $I_D = 16\text{ A}$	44	62	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{ V}$ to $5\text{ V}$		25	35	nC
$Q_{gs}$	Gate to Source Charge			12.9		nC
$Q_{gd}$	Gate to Drain "Miller" Charge			9.2		nC

**Drain-Source Diode Characteristics**

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 2.1\text{ A}$ (Note 2)		0.69	1.2	V
		$V_{GS} = 0\text{ V}$ , $I_S = 16\text{ A}$ (Note 2)		0.78	1.3	
$t_{rr}$	Reverse Recovery Time	$I_F = 16\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$		69	110	ns
$Q_{rr}$	Reverse Recovery Charge			94	150	nC

Notes:

1.  $R_{\theta JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta CA}$  is determined by the user's board design.a.  $45\text{ }^{\circ}\text{C}/\text{W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.b.  $115\text{ }^{\circ}\text{C}/\text{W}$  when mounted on a minimum pad of 2 oz copper.2. Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty cycle < 2.0%.3.  $E_{AS}$  of 726 mJ is based on starting  $T_J = 25\text{ }^{\circ}\text{C}$ ,  $L = 3\text{ mH}$ ,  $I_{AS} = 22\text{ A}$ ,  $V_{DD} = 100\text{ V}$ ,  $V_{GS} = 10\text{ V}$ , 100% test at  $L = 0.1\text{ mH}$ ,  $I_{AS} = 69\text{ A}$ .4. Pulse  $I_d$  please refer to Fig.11 SOA curve for detail.

5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal &amp; electro-mechanical application board design.

# Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

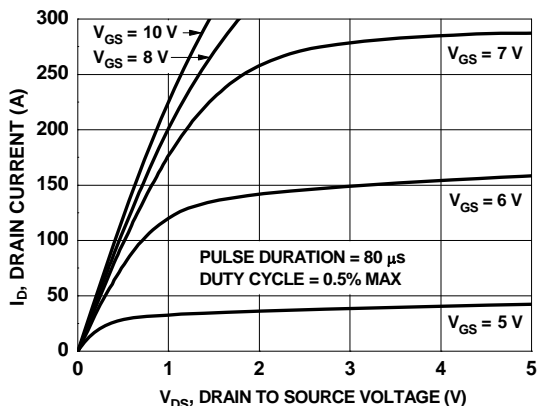


Figure 1. On Region Characteristics

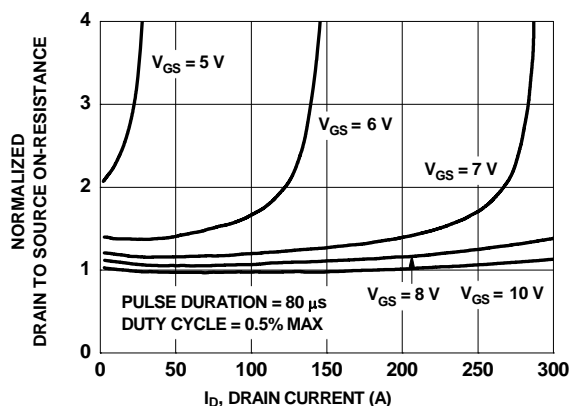


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

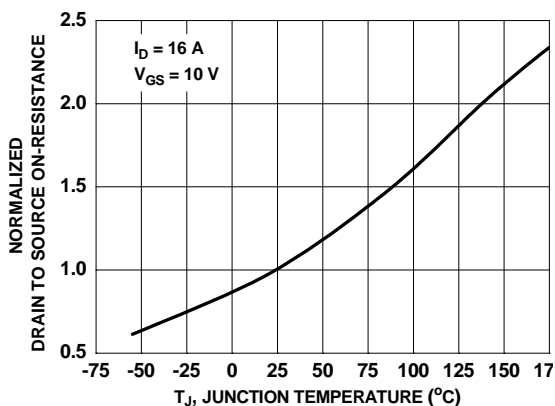


Figure 3. Normalized On Resistance vs Junction Temperature

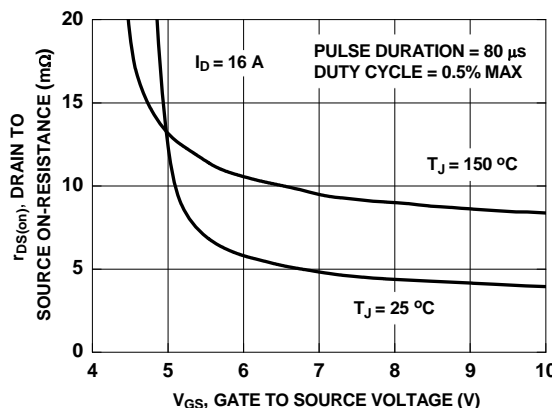


Figure 4. On-Resistance vs Gate to Source Voltage

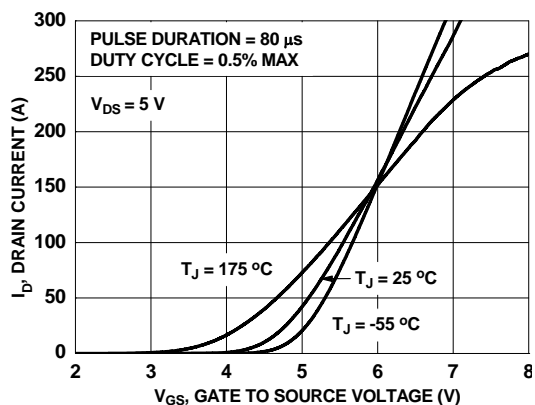


Figure 5. Transfer Characteristics

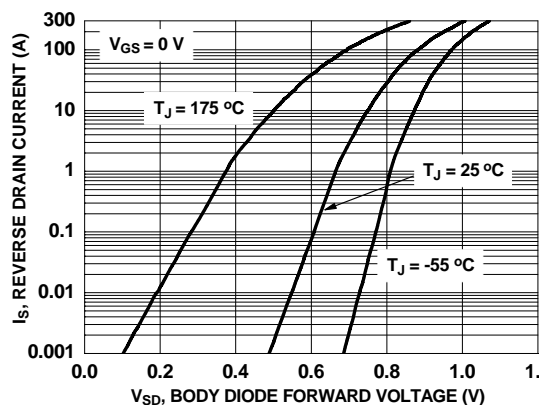


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

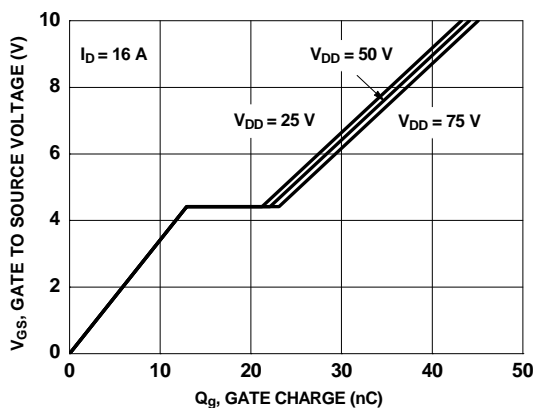


Figure 7. Gate Charge Characteristics

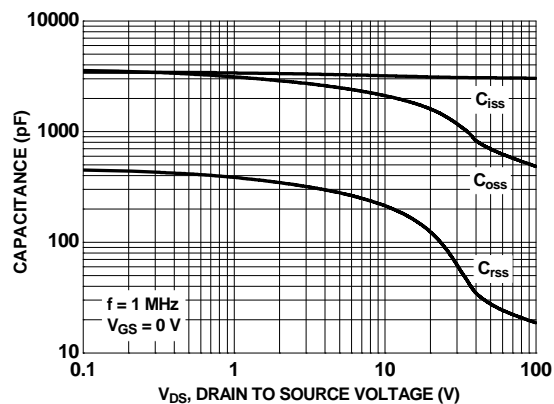


Figure 8. Capacitance vs Drain to Source Voltage

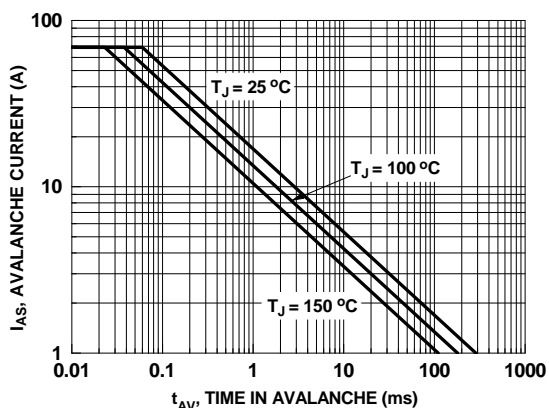


Figure 9. Unclamped Inductive Switching Capability

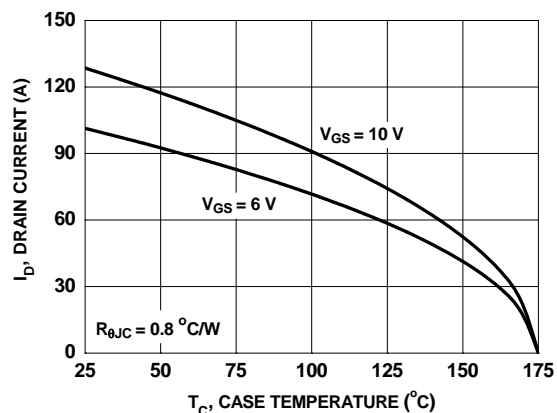


Figure 10. Maximum Continuous Drain Current vs Case Temperature

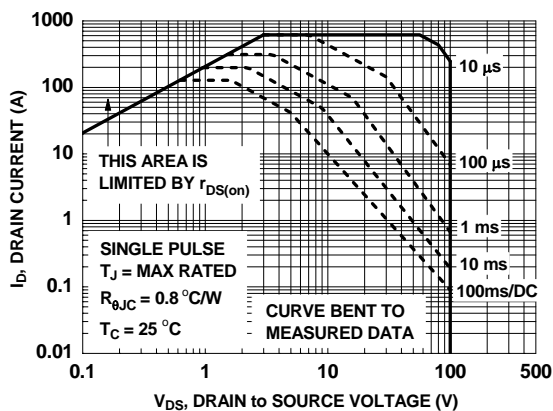


Figure 11. Forward Bias Safe Operating Area

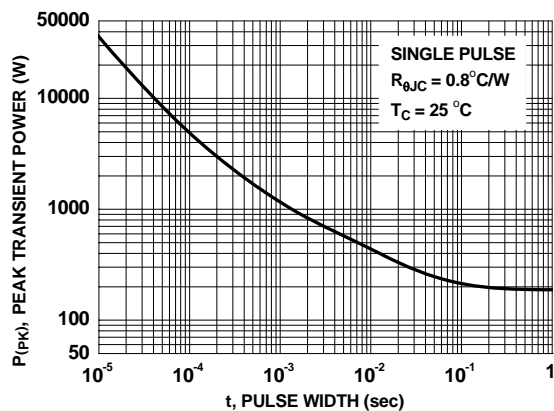


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted

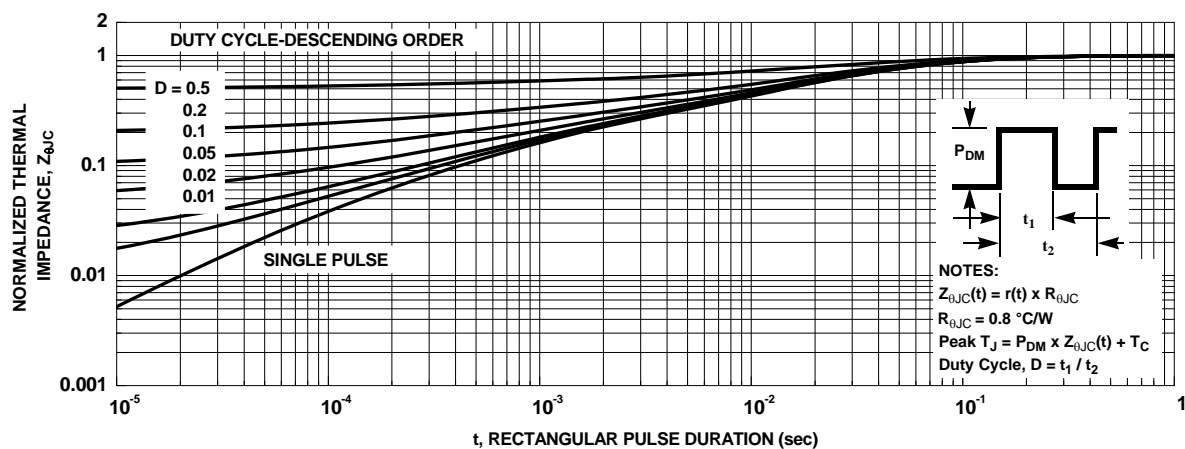
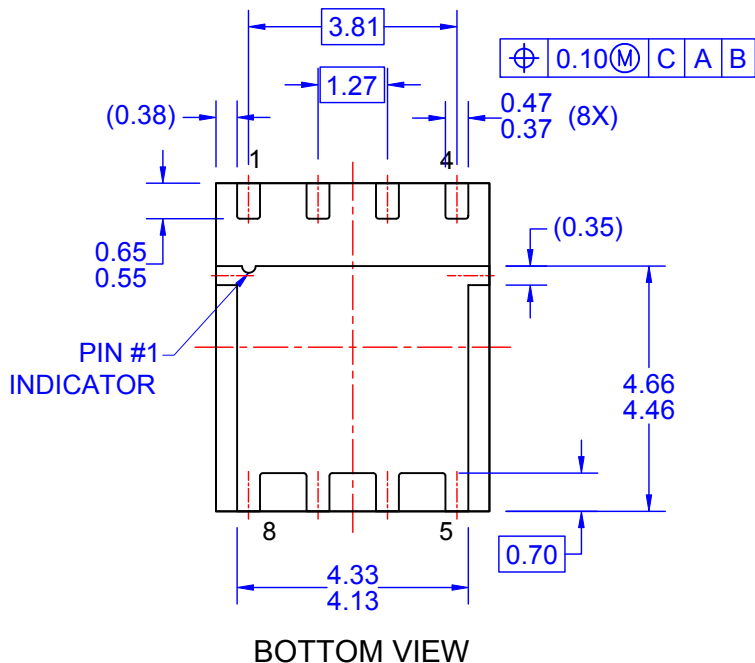
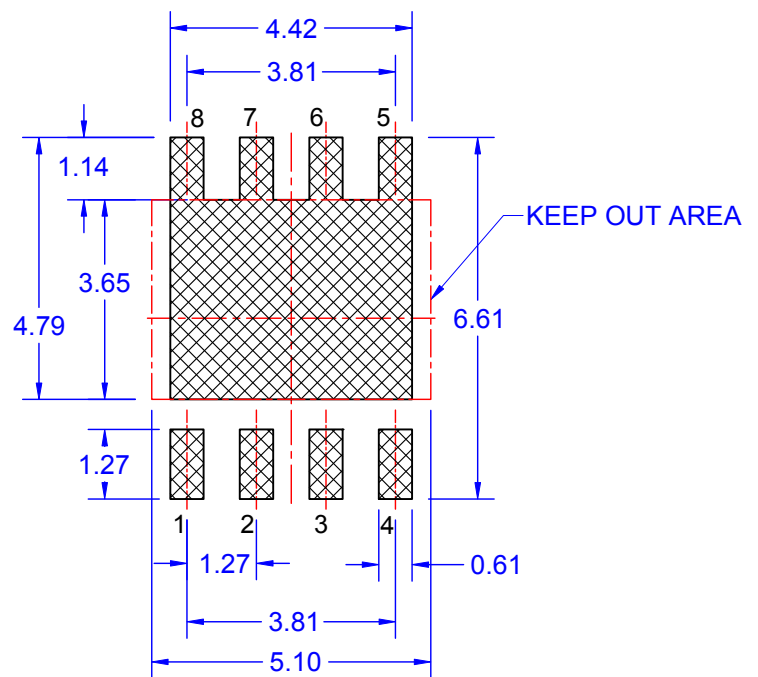
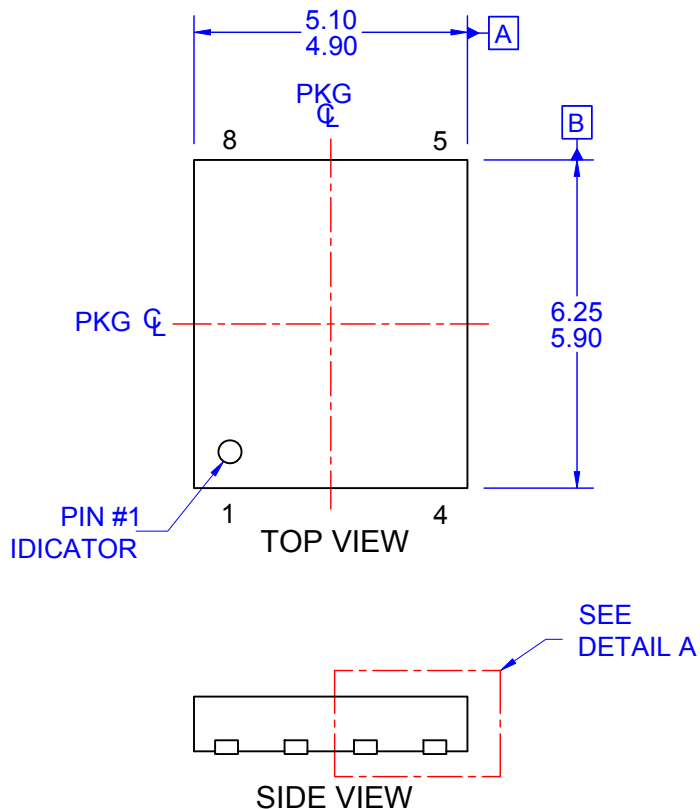
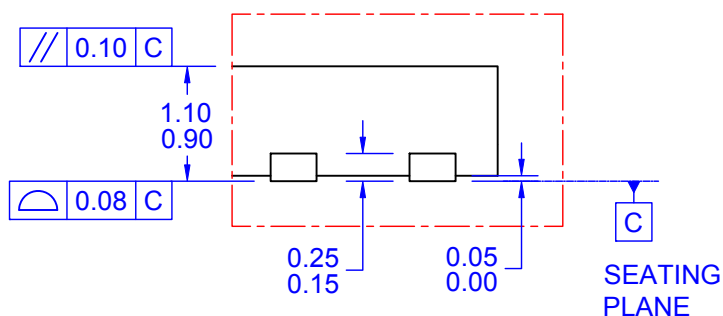


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA,
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
  - D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
  - E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.
  - F) DRAWING FILE NAME: PQFN08JREV3.



#### DETAIL A

SCALE: 2:1



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